

GRID 4iP

HIGH PERFORMANCE COMPUTING

19-inch - 2U/4 nodes

Key Features



**19-inch - 2U 4 Nodes 2
CPU/Node 6x 2,5"/
Node**



**Dual Intel Xeon
Scalable 3r generation
Processors**



**16x DDR4 @ 3200MHz/
node
Up to 4TB/node**



**2x PCIe 4.0 OCP 3.0/
node**



**2000W redundant
Platinum**



**IPMI / iKVM with
ASPEED® AST2500**



Air Cooling

Front view



3rd Gen Intel® Xeon® Scalable Processors

The GRID 4iP is built with the latest Intel® Xeon® Scalable Processors, and designed for the demand of high scalability, high density computing, and widest range of workloads. 3rd Gen Intel® Xeon® Scalable processors offer a balanced architecture with built-in acceleration and advanced security capabilities.

Highest density for the highest performance

With up to 320 cores per node, the GRID 4iP offers the highest density possible to optimise your operations. From high core density to run your HPC workloads to adaptive configuration to manage your Cloud and virtualized environments, the GRID 4iP is up to any challenges.

Cloud and Enterprise Made Flexible

The latest 3rd Gen Intel® Xeon® Scalable processors are built upon years of cloud innovation, tuned to your unique needs with built-in AI and Intel® deep learning boost and advanced security capabilities.

Back view



SPECIFICATIONS

System	Model	GRID 4iP
	Form Factor	19-inch 2U
	Nodes	4
	Dimension	805x 446 x 87.5mm (D x W x H)
Storage	Internal type	24x 2.5" Gen4 U.2 hot-swappable SSD bays. 6x 2.5"/Node All storage bays are compatible with SATA devices 2x Onboard M.2 slot: - M-key, PCIe x2 Gen4 / Drive or SATA - Supports 2280 M.2 SSDs
Motherboard	CPU	Dual Intel® XEON® 3rd Generation Scalable Processors family
	Chipset	System on Chip
	Expansion slots	2x OCP 3.0 Mezzanine (Gen4 x16)
	BMC	Aspeed® AST2500
CPU	Type	2x Socket P+ (LGA 4189) Intel® XEON® 3rd Generation Scalable Processors family
	TDP	TDP up to 270W
	Compatibility	Compatible with Intel® XEON® 3rd Generation Scalable Processors Total of 8x LGA 4189 Socket P+
Memory	Total Slots	16x (8-channel per CPU, 8 DIMM per CPU)
	Capacity per DIMM	RDIMM/LRDIMM modules up to 128GB supported 3DS RDIMM/LRDIMM modules up to 256GB supported
	Memory Speed	Up to 3200 MHz
Network		1x Management Port Available options from OCP3 slot : 4x 10/25Gbps Ethernet SFP28 2x 100Gbps Ethernet or In iniband QSFP28 1x 200Gbps Ethernet or In iniband QSFP56
Rear I/O	Ports	Per Node: 2x USB 3.0 ports 1x Management port RJ45
Management Solution	Software	AMI MegaRAC SP-X
	Out of Band Remote Management	WebGUI, Intelligent Platform Management Interface (IPMI) and Redfish® API
Front I/O	Button	Power on/off
Power Supply	Type	1+1 2000W (240V) 80 PLUS Platinum power supply
	Power rating	200-240 Vac, 15.5A (x2), 50-60Hz